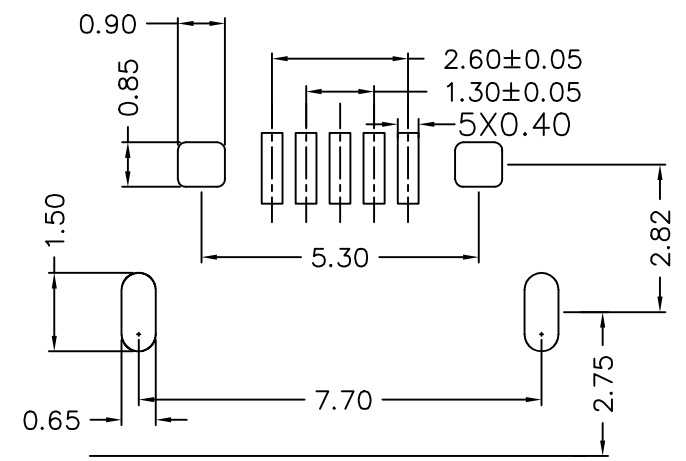
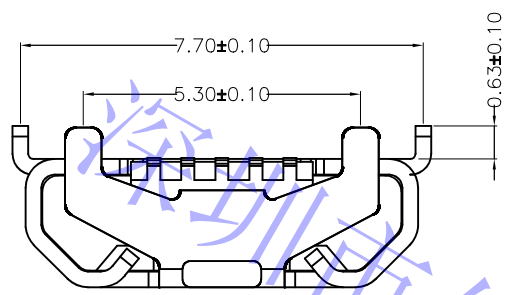
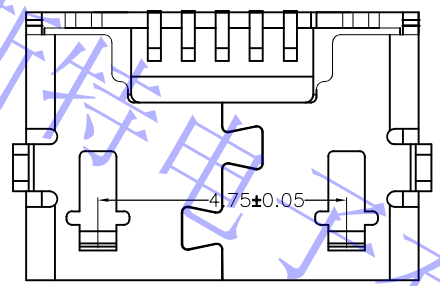
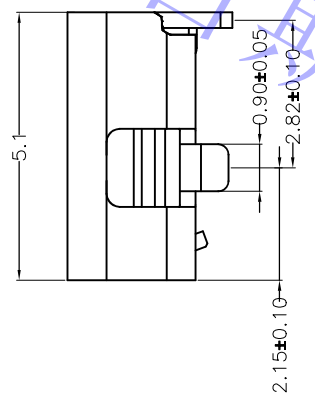
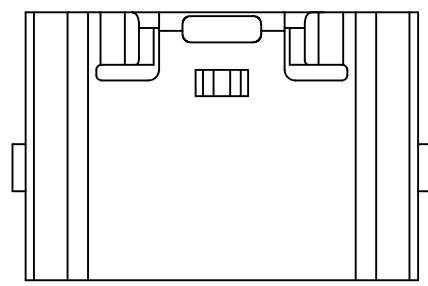


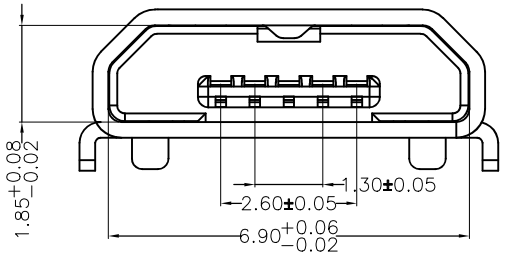
修改序号	修改说明	签名	日期
A/0			



PCB LAYOUT



Note:
 1.Material:
 1.1 Housing: High temperature thermoplastic with g.f,UL94v-0
 1.2 Contact: copper alloy,t=0.15mm
 1.3 Shell: copper alloy&SUS
 2.Specification:
 2.1 Current rating: 1 A Max.
 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
 2.3 Contact resistance: 30 mΩ Max.
 2.4 Insulation resistance: 100 MΩ Min.
 2.5 Total mating force: 3.57 Kgf Max.
 2.6 Total unmating force: 1.0 Kgf Min.0.81~2.05 Kgf Min.after 10000 insertion/extraction cycles
 2.7 Temperature range: -30°C~80°C



尺寸	允许公差
X.	?0.50
.X	?0.20
.XX	?0.10
.XXX	?0.03
角度	?1.00?

亿利百斯特 **深圳市亿利百斯特电子有限公司**

图纸类型		图纸名称:	
产品工程图		MICRO 5P/F B 反向牛角内DIP 0.6(7.7*5.3)无卷边	
设计	zhu yin	2011.07.21	产品料号
审核			视图
			版号: A/0